

L Number	Hits	Search Text	DB	Time stamp
1	1012	repair\$5 same defect\$5 same laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/02 12:32
8	219	(repair\$5 same defect\$5 same laser) and (remov\$5 with portion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/02 12:33
15	166	((repair\$5 same defect\$5 same laser) and (remov\$5 with portion)) and metal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/02 12:35
16	165	((repair\$5 same defect\$5 same laser) and (remov\$5 with portion)) and (metal metallic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/02 12:36
23	1691	(repair repaired repairing) with pattern	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/02 12:44
30	49	((repair\$5 same defect\$5 same laser) and (remov\$5 with portion)) and (metal metallic)) and ((repair repaired repairing) with pattern)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/02 12:36
37	366	((repair repaired repairing) with (pattern substrate)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/02 12:46
44	125	((repair repaired repairing) and (pattern substrate) and laser).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/02 12:46
-	1434	(219/121.85).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/02 12:32
-	1	("6331348").PN.	USPAT	2002/02/28 16:31

-	8623	(metal\$5 near2 organic) same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:33
-	79389	semiconductor adj laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:34
-	1349	((metal\$5 near2 organic) same substrate) and (semiconductor adj laser)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:34
-	1	((219/121.85).CCLS.) and (((metal\$5 near2 organic) same substrate) and (semiconductor adj laser))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:42
-	7294	((428/209) or (427/555) or (427/96) or (427/383.1) or (219/121.85)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:43
-	110	((metal\$5 near2 organic) same substrate) and (((428/209) or (427/555) or (427/96) or (427/383.1) or (219/121.85)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:43
-	60	(semiconductor adj laser) and (((428/209) or (427/555) or (427/96) or (427/383.1) or (219/121.85)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:43
-	5	((metal\$5 near2 organic) same substrate) and (((428/209) or (427/555) or (427/96) or (427/383.1) or (219/121.85)).CCLS.)) and ((semiconductor adj laser) and (((428/209) or (427/555) or (427/96) or (427/383.1) or (219/121.85)).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:44
-	8147	repair\$5 with metal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:47
-	49	((metal\$5 near2 organic) same substrate) and (repair\$5 with metal\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:54

-	14	((metal\$5 near2 organic) same substrate) and (repair\$5 with metal\$5)) and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 16:57
-	36503	substrate same metal\$5 same pattern	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:01
-	213	(repair\$5 with metal\$5) and (substrate same metal\$5 same pattern)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:01
-	113	((repair\$5 with metal\$5) and (substrate same metal\$5 same pattern)) and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:01
-	461	repair\$5 with metal\$5 with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:48
-	335	(repair and substrate).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:48
-	189	(repair and substrate).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:49
-	3	(repair\$5 with metal\$5 with substrate) and ((repair and substrate).clm.) and ((repair and substrate).ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:49
-	40	(repair\$5 with metal\$5 with substrate) and ((repair and substrate).clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:49
-	28	(repair\$5 with metal\$5 with substrate) and ((repair and substrate).ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:49

65	((repair\$5 with metal\$5 with substrate) and ((repair and substrate).clm.)) ((repair\$5 with metal\$5 with substrate) and ((repair and substrate).ti.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:49
630	gold adj paste	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:59
514	((repair and substrate).clm.) ((repair and substrate).ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 17:59
1	(gold adj paste) and (((repair and substrate).clm.) ((repair and substrate).ti.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:00
25	((repair\$5 with metal\$5 with substrate) and ((repair and substrate).clm.)) ((repair\$5 with metal\$5 with substrate) and ((repair and substrate).ti.)) and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:02
9732	((liquid adj crystal adj display) lcd) same (glass adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:47
8	(repair\$5 with metal\$5 with substrate) and (((liquid adj crystal adj display) lcd) same (glass adj substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:27
7	((repair\$5 with metal\$5 with substrate) and (((liquid adj crystal adj display) lcd) same (glass adj substrate))) and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:31
4	(metallic adj organic) with (defect\$5 repair\$5) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:33
4	(("4187128") or ("4859256") or ("5464990") or ("5738733")).PN.	USPAT	2002/02/28 18:35
562	(228/119).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:38

28	((228/119).CCLS.) and gold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:39
45	((228/119).CCLS.) and organ\$7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:39
323	((228/119).CCLS.) and metal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:40
178	((228/119).CCLS.) and defect\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:40
47	((228/119).CCLS.) and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:41
8	((((228/119).CCLS.) and gold) and ((228/119).CCLS.) and organ\$7)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:41
41	((((228/119).CCLS.) and organ\$7) and ((228/119).CCLS.) and metal\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:41
17	((((228/119).CCLS.) and gold) and ((228/119).CCLS.) and defect\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:41
5	(((((228/119).CCLS.) and organ\$7) and ((228/119).CCLS.) and metal\$5)) and (((228/119).CCLS.) and gold) and ((228/119).CCLS.) and defect\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:42
4	(((((228/119).CCLS.) and laser) and (((228/119).CCLS.) and organ\$7) and ((228/119).CCLS.) and metal\$5)) and (((228/119).CCLS.) and gold) and ((228/119).CCLS.) and defect\$6)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:46

26	((liquid adj crystal adj display) lcd) same (glass adj substrate) same repair\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:53
35	(glass adj substrate) same repair\$5 same laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/28 18:53